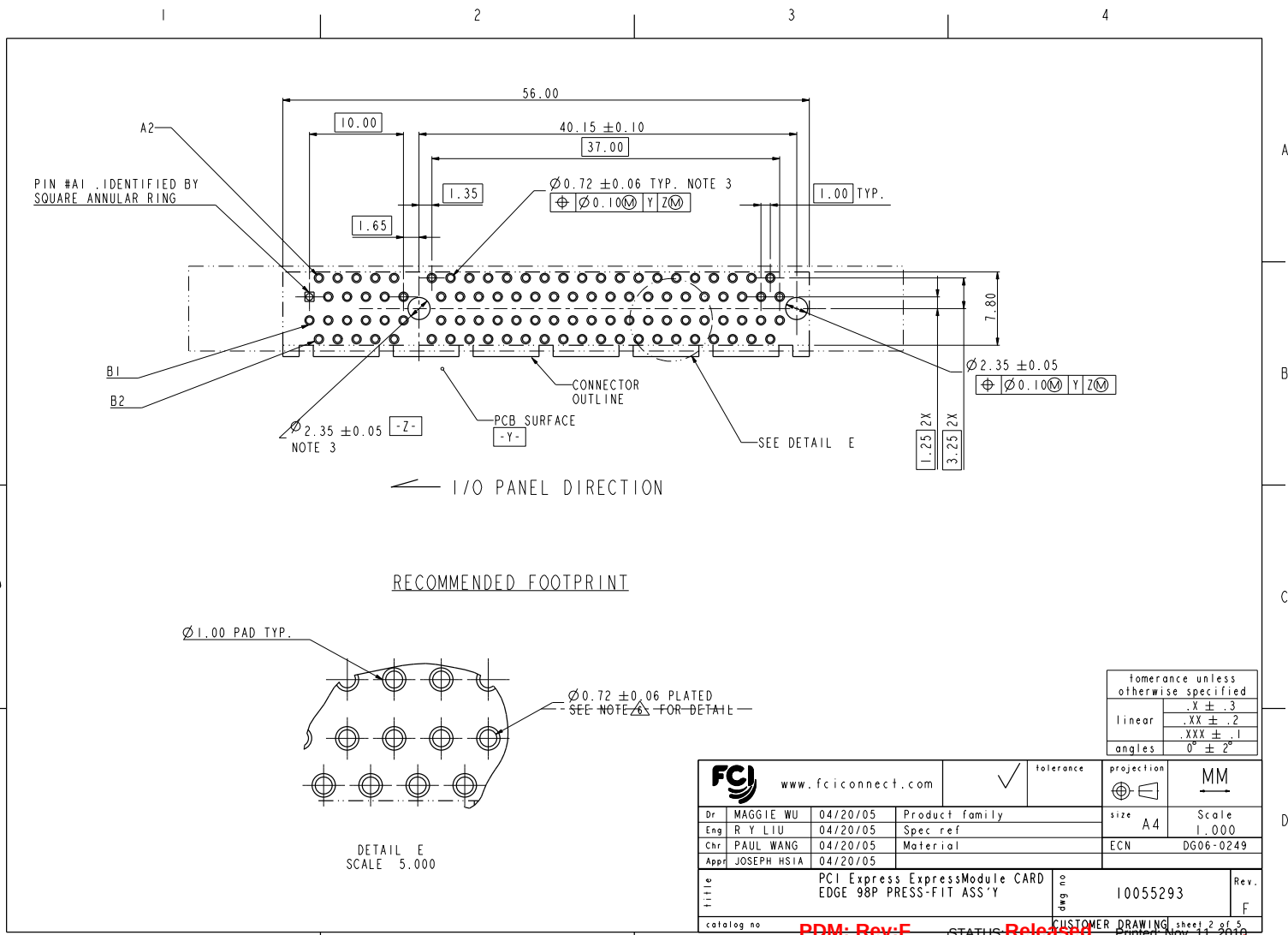


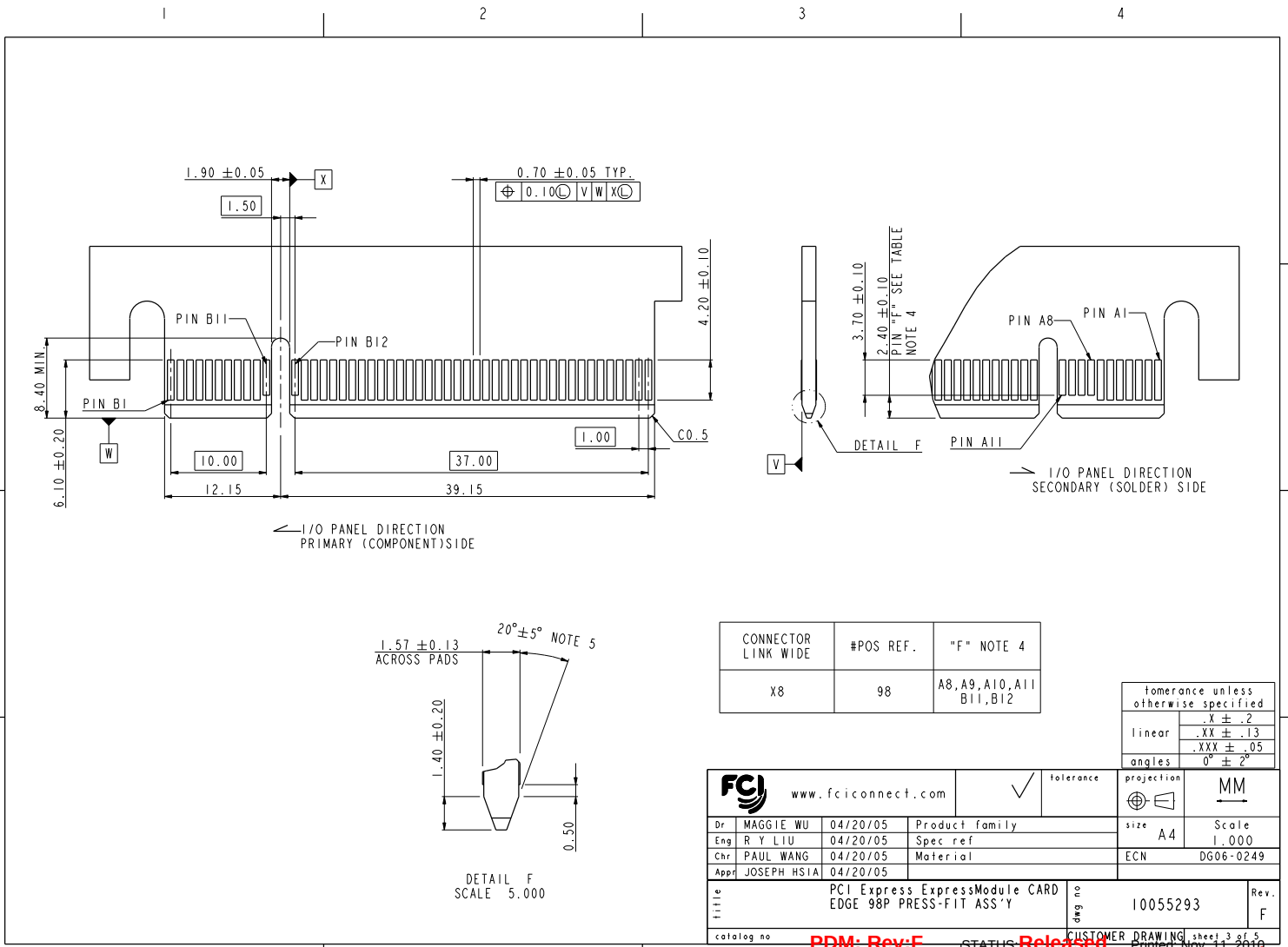
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PDM: Rev:F STATUS: Released

Printed: Nov 11, 2010

NOTES:

1. MATERIAL:
HOUSING: HIGH TEMPERATURE NYLON, GLASS FILLED UL94V-0 RATED. SUITABLE FOR REFLOW SOLDERING.
TERMINAL: COPPER ALLOY
PLATING: 50u" NICKEL UNDERPLATE ALL OVER
CONTACT AREA PLATING - SEE PRODUCT NUMBER CODE
SOLDER TAIL: TIN - 100u" MIN. OVER 50u" NICKEL OR TIN/LEAD 100u" MIN. SEE PRODUCT NUMBER CODE
2. PRODUCT SPECIFICATION: GS-12-319
THE HORIZONTAL AXIS FOR THE HOLE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE TWO Ø2.35 HOLES.
THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM Z.
- NO TIE BAR PERMITTED FROM CARD EDGE TO LEADING EDGE OF PAD FOR PINS A1 AND PIN NUMBERS "F".
- CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.
- ALL PLATED THRU HOLES SHOULD BE 0.76-0.83 mm DIA DRILLED AND 0.025mm ~ 0.05mm. ELECTRO-DEPOSITED COPPER THK ON THROUGH HOLE WALL.
7. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

- a-PLATING:
- "LF" MEANS THE PRODUCT IS LEAD-FREE, 2um MINIMUM MATTE TIN OVER 1.27um MINIMUM NICKEL UNDERPLATE.
- b-MANUFACTURING PROCESS COMPATIBILITY
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C±5°C SOLDER BATH TEMPERATURE FOR 10 SECONDS IN A REFLOW SOLDER APPLICATION WITH A 2.36mm AND 4.19mm MIN THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10055293 - X X X X X X X X

HOUSING COLOR OPTIONS
1-BLACK

PEGS OPTIONS
0-PLASTIC PEGS

TERMINAL PLATING OPTIONS

0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA -----COMPATIBLE RoHS

3-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN/LEAD TAIL AREA -----RoHS COMPLIANT EXCEPT Pb

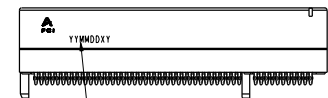
LEAD FREE OPTION
"LF" FOR TERMINAL PLATING OPTION 0
LEAVE BLANK FOR TERMINAL PLATING OPTION 3

PACKAGING OPTIONS
T-TRAY PACKAGING

RESERVE
0

TAIL LENGTH OPTIONS

	DIM "D"	SUGGESTED PCB THICKNESS
0	2.00±0.20	2.36
1	3.25±0.20	4.19



Date code:
"YY" means year number
"MM" means month number
"DD" means day number
"X" means manufacture location
"D" means made in Dongguan site
"Y" means shift number
If date code is 060626D1, it means this part is made by shift 1 in 2006/06/26 and manufactured in Dongguan site
Date code should be laser mark

tolerance unless otherwise specified	
linear	.X ± .3 .XX ± .2 .XXX ± .1
angles	0° ± 2°

www.fciconnect.com		☒ tolerance	☐ projection	☐ MM
Dr	MAGGIE WU	04/20/05	Product family	
Eng	R Y LIU	04/20/05	Spec ref	
Chr	PAUL WANG	04/20/05	Material	
Appr	JOSEPH HSIA	04/20/05	ECN DG06-0249	
PCI Express ExpressModule CARD EDGE 98P PRESS-FIT ASS'Y			size A4	Scale 1:000
catalog no			drawing no 10055293	Rev. F

PDM: Rev:F

STATUS:Released

CUSTOMER DRAWING sheet 4 of 5
Printed: Nov 11, 2010

A

B

C

D

E

F

G

H

I

J

K

L

M

N

O

P

Q

R

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T

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V

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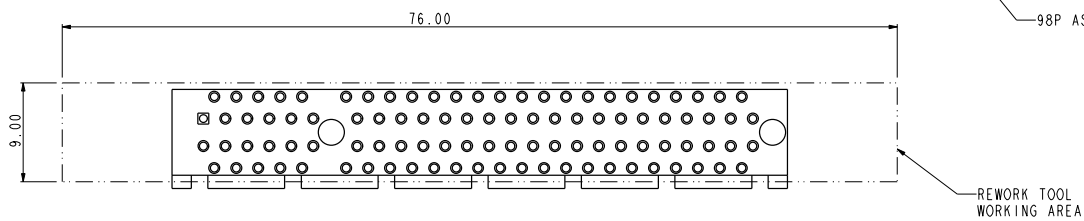
X

Y

Z

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SCALE 2.000

		www.fciconnect.com			tolerance			
Dr	MAGGIE WU	04/20/05	Product family			size	A4	Scale
Eng	R Y LIU	04/20/05	Spec ref					1.000
Chr	PAUL WANG	04/20/05	Material			ECN	DG06-0249	
Appr	JOSEPH HSIA	04/20/05						
title			PCI Express ExpressModule CARD EDGE 98P PRESS FIT ASS'Y				Rev.	
catalog no			10055293				F	
BDM: Rev.E			CUSTOMER				sheet 5 of 5	

PDM: Rev:F

STATUS:Released

CUSTOMER